60V P-Channel Trench Power MOSFET

General Description

The SJP60P220 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as -4.5V. This device is suitable for use as a wide variety of applications.

Features

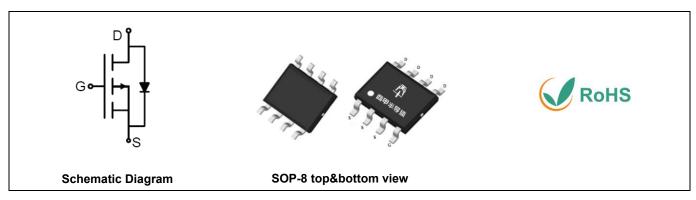
- Low Gate Charge
- 100% UIS Tested, 100% DVDS Tested
- High Power and current handing capability
- Lead free product is acquired

Application

- Load switch
- DC/DC converter for LCD display

Key Performance Parametes

Parameter	Value	Unit
V _{DS}	-60	٧
R _{DS(ON)_TYP}	25	mΩ
I _D	-9	Α
Q _G	68	nC



Package Marking and Ordering Information

Device/Ordering Code	Marking	Package	Packing	Reel Size	Tape width	Quantity
SJP60P220	SJP60P220	SOP-8	Tape	1	1	4000 Pcs

Table 1. Absolute Maximum Ratings (T_c=25℃ unless otherwise noted)

Symbol	Parameter	Limit	Unit	
V _{DS}	Drain-Source Voltage (V _{GS} =0V)	-60	V	
V _G s	Gate-Source Voltage (V _{DS} =0V)	±20	V	
1-	Drain Current-Continuous(T _A =25°C)		А	
I _D	Drain Current-Continuous(T _A =100℃)	-5.7	А	
I _{DM} (pluse)	Drain Current-Continuous@ Current-Pulsed (Note 1)	-36	А	
В	Maximum Power Dissipation(T _A =25℃)		W	
P _D	Maximum Power Dissipation(T _A =100℃)	1.8	W	
Eas	Avalanche energy (Note 2)	196	mJ	
TJ, TSTG	Operating Junction and Storage Temperature Range	-55 To 175	C	

Table 2. Thermal Characteristic

Symbol	Parameter	Тур	Max	Unit
R _θ JA	Thermal Resistance, Junction-to-Ambient		28.5	°C/W



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Table 3. Electrical Characteristics (T_J=25℃ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Тур	Max	Unit	
On/Off States							
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V I _D =-250μA	-60			V	
	7 0 1 1/1 5 : 0 1	V _{DS} =-60V, V _{GS} =0V T _J =25℃			-1	μA	
IDSS	Zero Gate Voltage Drain Current	V _{DS} =-60V, V _{GS} =0V T _J =125 °C			-100	μΑ	
Igss	Gate-Body Leakage Current	V _{GS} =±20V, V _{DS} =0V			±100	nA	
$V_{GS(th)}$	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =-250μA	-1		-2.5	V	
g FS	Forward Transconductance	V _{DS} =-5V, I _D =-15A		27		S	
R _{DS(ON)}	Drain-Source On-State Resistance	V _{GS} =-10V, I _D =-15A T _J =25℃		25	31.3	mΩ	
R _{DS(ON)}	Drain-Source On-State Resistance	V _{GS} =-4.5V, I _D =-10A T _J =25°C		30.5	40.6	mΩ	
Dynamic Chara	acteristics	,		•			
Ciss	Input Capacitance			3540		pF	
Coss	Output Capacitance	V _{DS} =-25V,V _{GS} =0V, f=1.0MHz		143		pF	
C _{rss}	Reverse Transfer Capacitance			130		pF	
Rg	Gate resistance	V _{GS} =0V, V _{DS} =0V, f=1.0MHz		4.4		Ω	
Switching Para	meters						
t _{d(on)}	Turn-on Delay Time			12.2		nS	
tr	Turn-on Rise Time	V _{GS} =-10V, V _{DS} =-30V,		10		nS	
$t_{d(off)}$	Turn-Off Delay Time	R_L =2Ω, R_{GEN} =3Ω		64		nS	
t_f	Turn-Off Fall Time			14		nS	
Qg	Total Gate Charge			68		nC	
Q _{gs}	Gate-Source Charge	V _{GS} =-10V, V _{DS} =-30V, I _D =-15A		11		nC	
Q_{gd}	Gate-Drain Charge			13		nC	
Source-Drain Diode Characteristics							
I _{SD}	Source-Drain Current (Body Diode)				-9	Α	
V _{SD}	Forward on Voltage (Note 3)	V _{GS} =0V, I _S =-15A			-1.2	V	
t _{rr}	Reverse Recovery Time	I _F =-15A, di/dt=-100A/μs		26		ns	
Qrr	Reverse Recovery Charge	I _F =-15A, di/dt=-100A/μs		29		nC	

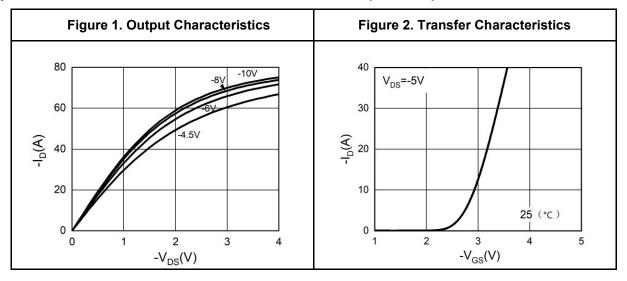
Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature.

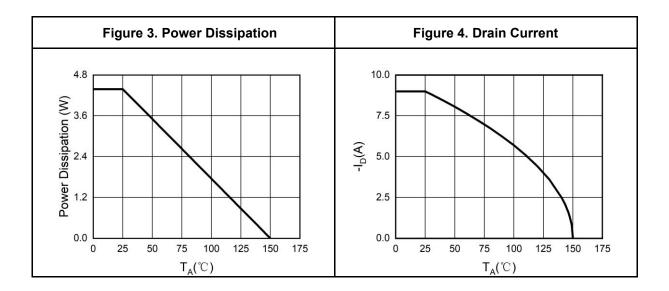
Notes 2.E_{AS} condition: $T_J=25^{\circ}C$, $V_{DD}=-40V$, $V_{G}=-10V$, $Rg=25\Omega$, L=0.5mH.

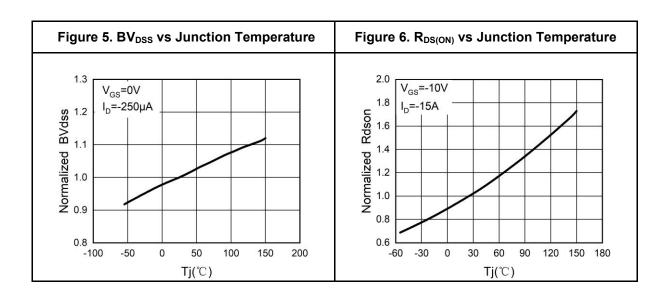
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Typical Electrical And Thermal Characteristics (Curves)

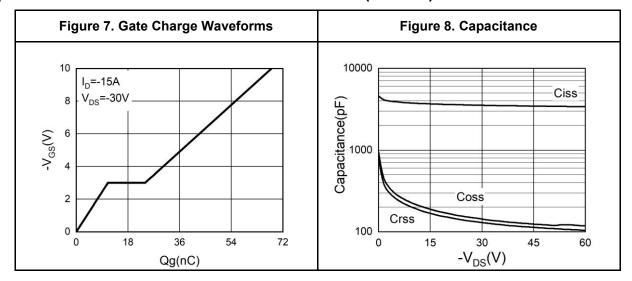


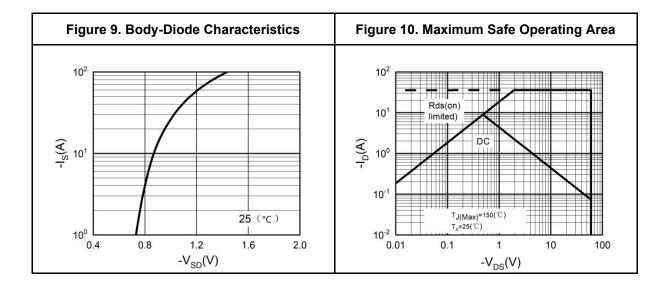






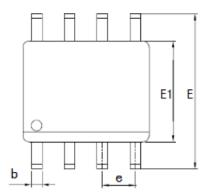
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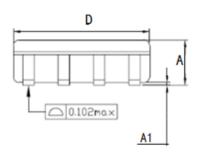


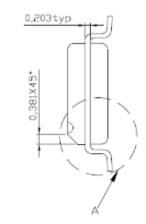


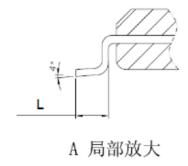


SOP-8 Package Information









COMMON DIMENSIONS				
SYMBO	mm			
L	MIN	NOM	MAX	
Α	1. 35	1. 55	1. 75	
A1	0. 1	0. 15	0. 2	
b	0. 346	0. 406	0. 466	
D	4. 8	4. 89	4. 98	
E	5. 75	6. 00	6. 25	
E1	3. 81	3. 90	3. 99	
e	1. 27TYP			
L	0. 406	0. 838	1. 27	

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Attention

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